

## Description

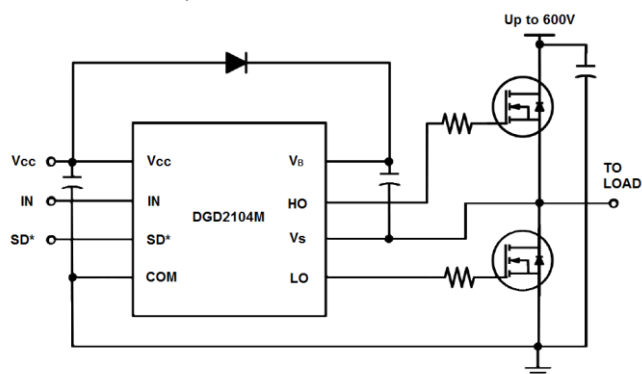
The DGD2104M is a high-voltage / high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High-voltage processing techniques enable the DGD2104M's high side to switch to 600V in a bootstrap operation.

The DGD2104M logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction.

The DGD2104M is offered in the SO-8 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

## Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers




Typical Configuration

## Features

- Floating High-Side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuration
- 290mA Source / 600mA Sink Output Current Capability
- Designed for Enhanced Performance in Noisy Motor Applications
- Outputs Tolerant to Negative Transients
- Internal Dead Time to Protect MOSFETs
- Wide Low-Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (IN and SD\*) 3.3V Capability
- Schmitt Triggered Logic Inputs
- Undervoltage Lockout for V<sub>CC</sub> (Logic and Low Side Supply)
- Extended Temperature Range: -40°C to +125°C
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads Solderable per MIL-STD-202, Method 208 
- Weight: 0.074 grams (Approximate)



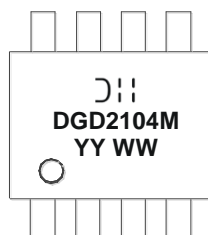
SO-8 (Type TH)  
Top View


## Ordering Information (Note 4)

Product	Marking	Reel Size (inch)	Tape Width (mm)	Quantity per Reel
DGD2104MS8-13	DGD2104M	13	12	2,500

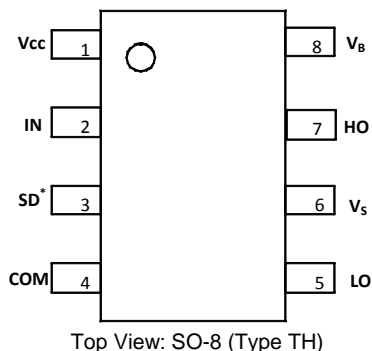
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



 = Manufacturer's Marking  
 DGD2104M = Product Type Marking Code  
 YY = Year (ex: 16 = 2016)  
 WW = Week (01 to 53)

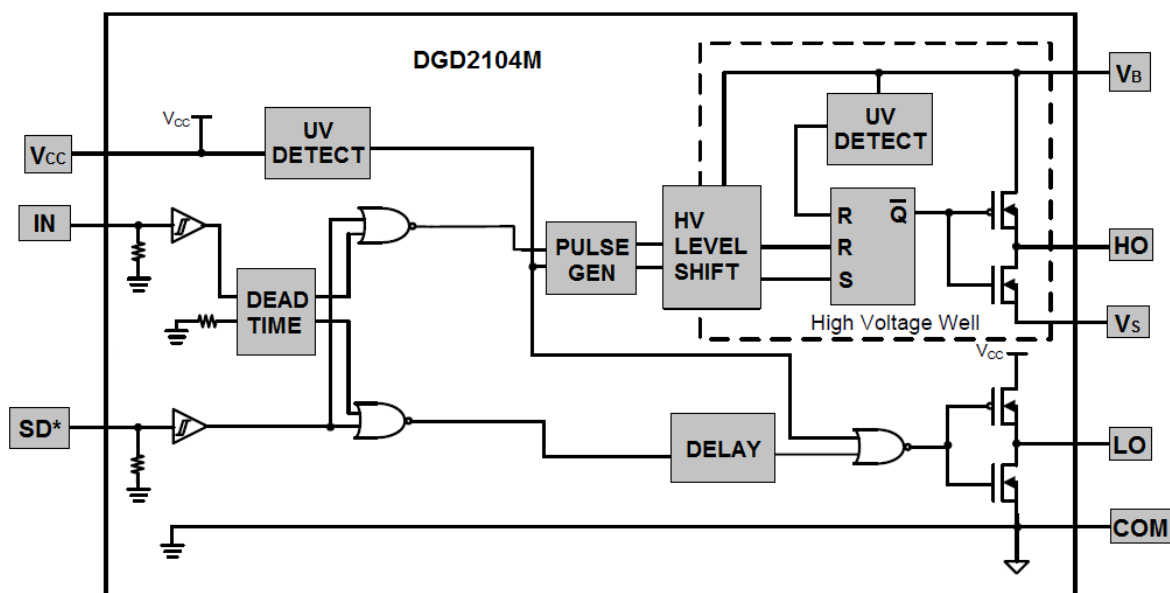
## Pin Diagrams



## Pin Descriptions

Pin Number	Pin Name	Function
1	V <sub>CC</sub>	Logic and Low Side Supply
2	IN	Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO
3	SD*	Logic input for Shutdown, Enabled Low
4	COM	Low-Side and Logic Return
5	LO	Low-Side Gate Drive Output
6	V <sub>S</sub>	High-Side Floating Supply Return
7	HO	High-Side Gate Drive Output
8	V <sub>B</sub>	High-Side Floating Supply

## Functional Block Diagram



## Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V <sub>B</sub>	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	V <sub>S</sub>	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V
High-Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub> -0.3 to V <sub>B</sub> +0.3	V
Offset Supply Voltage Transient	dV <sub>S</sub> / dt	50	V/ns
Low-Side Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V
Low-Side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (IN and SD*)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P <sub>D</sub>	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	200	°C/W
Operating Temperature	T <sub>J</sub>	+150	°C
Lead Temperature (Soldering, 10s)	T <sub>L</sub>	+300	
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

## Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V <sub>B</sub>	V <sub>S</sub> + 10	V <sub>S</sub> + 20	V
High Side Floating Supply Offset Voltage	V <sub>S</sub>	(Note 6)	600	V
High Side Floating Output Voltage	V <sub>HO</sub>	V <sub>S</sub>	V <sub>B</sub>	V
Low Side Fixed Supply Voltage	V <sub>CC</sub>	10	20	V
Low Side Output Voltage	V <sub>LO</sub>	0	V <sub>CC</sub>	V
Logic Input Voltage (IN and SD*)	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Note: 6. Logic operation for V<sub>S</sub> of -5V to +600V. Logic state held for V<sub>S</sub> of -5V to -V<sub>BS</sub>.

## DC Electrical Characteristics

( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V, @ $T_A$  = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Logic "1" (IN) & Logic "0" (SD*) Input Voltage	$V_{IH}$	2.5	–	–	V	$V_{CC}$ = 10V to 20V
Logic "0" (IN) & Logic "1" (SD*) Input Voltage	$V_{IL}$	–	–	0.8	V	$V_{CC}$ = 10V to 20V
High Level Output Voltage, $V_{BIAS} - V_O$	$V_{OH}$	–	0.05	0.2	V	$I_O$ = 2mA
Low Level Output Voltage, $V_O$	$V_{OL}$	–	0.02	0.1	V	$I_O$ = 2mA
Offset Supply Leakage Current	$I_{LK}$	–	–	50	μA	$V_B = V_S = 600V$
Quiescent $V_{BS}$ Supply Current	$I_{BSQ}$	–	60	100	μA	$V_{IN} = 0V$ or 5V
Quiescent $V_{CC}$ Supply Current	$I_{CCQ1}$	–	350	500	μA	$V_{IN} = 0V$ or 5V, $SD^* = 5V$
Quiescent $V_{CC}$ Supply Current in Shutdown	$I_{CCQ2}$	–	590	750	μA	$V_{IN} = 0V$ or 5V, $SD^* = 0V$
Logic "1" Input Bias Current	$I_{IN+}$	–	3.0	10	μA	$V_{IN} = 5V$ , $SD^* = 0V$
Logic "0" Input Bias Current	$I_{IN-}$	–	–	5.0	μA	$V_{IN} = 0V$ , $SD^* = 5V$
$V_{CC}$ Supply Undervoltage Positive Going Threshold	$V_{CCUV+}$	8.0	8.9	9.8	V	–
$V_{CC}$ Supply Undervoltage Negative Going Threshold	$V_{CCUV-}$	7.4	8.2	9.0	V	–
$V_{BS}$ Supply Undervoltage Positive Going Threshold	$V_{BSUV+}$	4.5	5.5	6.5	V	–
$V_{BS}$ Supply Undervoltage Negative Going Threshold	$V_{BSUV-}$	4.2	5.2	6.2	V	–
Output High Short Circuit Pulsed Current	$I_{O+}$	130	290	–	mA	$V_O = 0V$ , $PW \leq 10\mu s$
Output Low Short Circuit Pulsed Current	$I_{O-}$	270	600	–	mA	$V_O = 15V$ , $PW \leq 10\mu s$

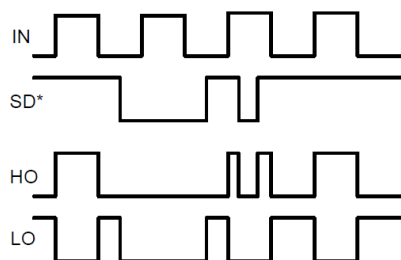
Note: 7. The  $V_{IN}$  and  $I_{IN}$  parameters are applicable to the two logic pins: IN and  $SD^*$ . The  $V_O$  and  $I_O$  parameters are applicable to the respective output pins: HO and LO.

## AC Electrical Characteristics

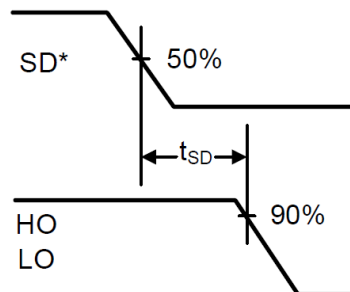
( $V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $C_L$  = 1000pF, @ $T_A$  = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Turn-On Propagation Delay	$t_{ON}$	–	680	820	ns	$V_S = 0V$
Turn-Off Propagation Delay	$t_{OFF}$	–	150	220	ns	$V_S = 600V$
Shutdown Propagation Delay	$t_{SD}$	–	160	220	ns	–
Delay Matching, HO and LO Turn-On / Turn-Off	$t_{DM}$	–	–	60	ns	–
Turn-On Rise Time	$t_R$	–	70	170	ns	$V_S = 0V$
Turn-Off Fall Time	$t_F$	–	35	90	ns	$V_S = 0V$
Deadtime: $t_{DT\ LO-HO}$ & $t_{DT\ HO-LO}$	$t_{DT}$	300	520	650	ns	–

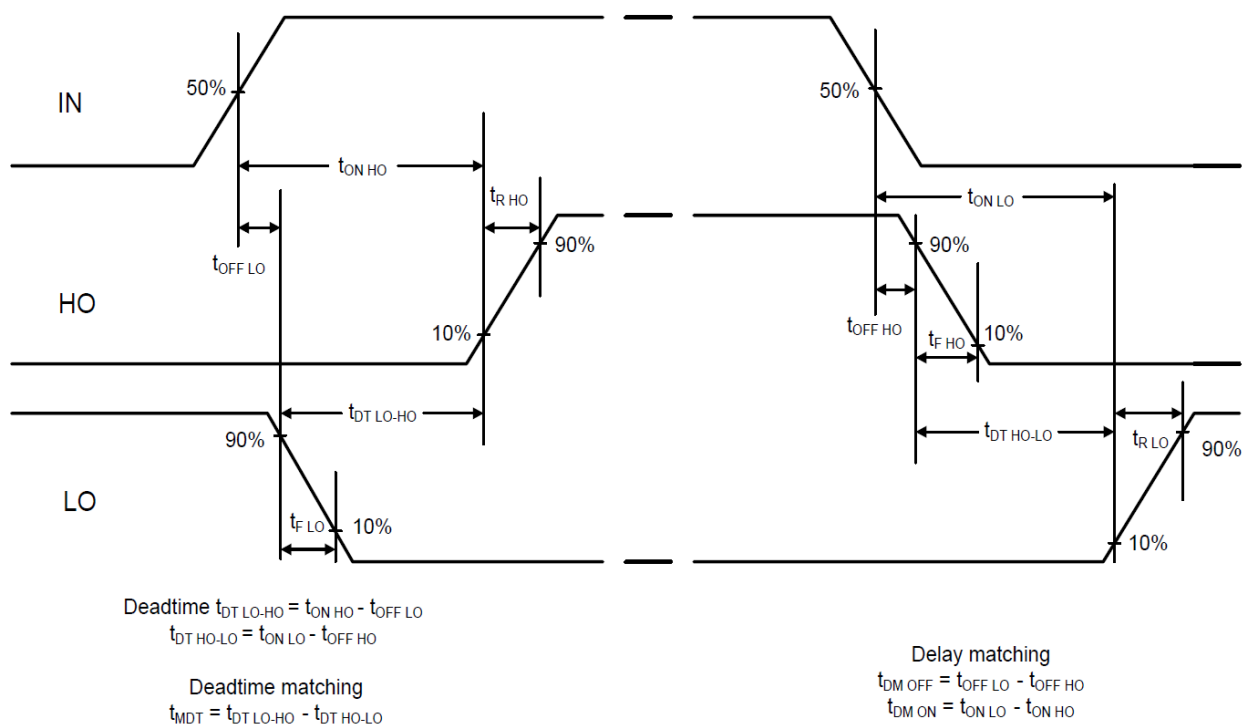
## Timing Waveforms



**Figure 1.** Input / Output Timing Diagram

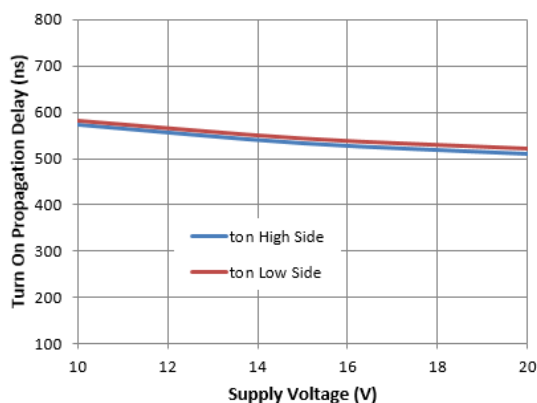


**Figure 2.** Shutdown Waveform Definition

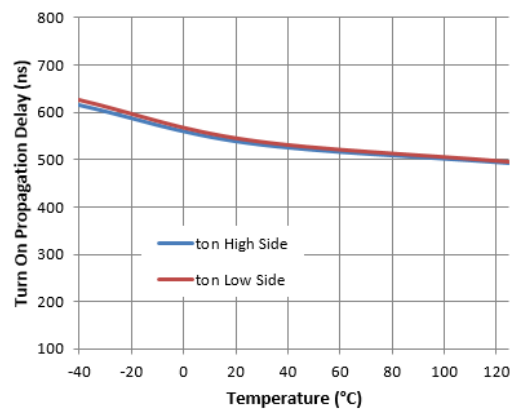


**Figure 3.** Switching Time Waveform Definitions

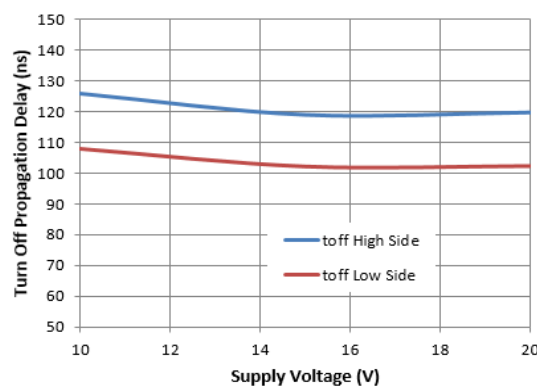
**Typical Performance Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)



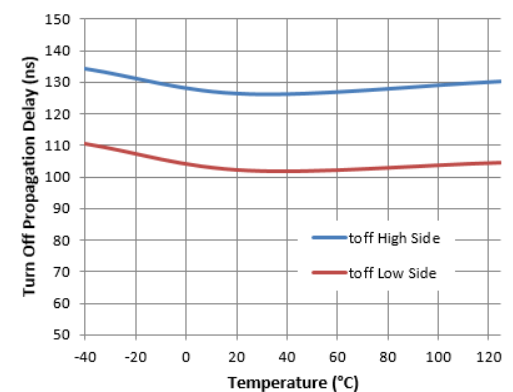
**Figure 4.** Turn-on Propagation Delay vs. Supply Voltage



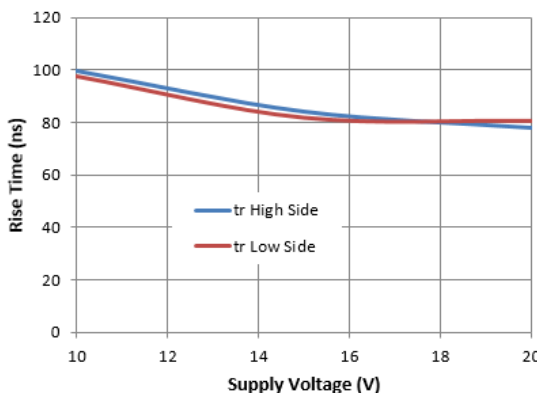
**Figure 5.** Turn-on Propagation Delay vs. Temperature



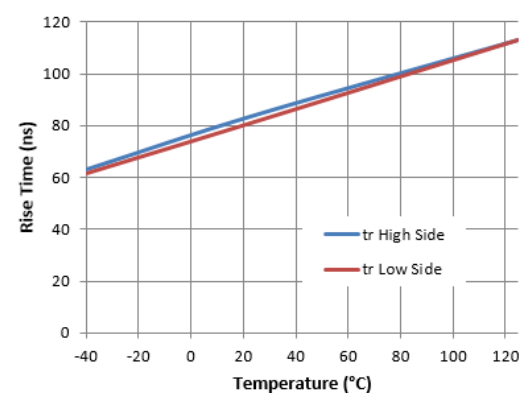
**Figure 6.** Turn-off Propagation Delay vs. Supply Voltage



**Figure 7.** Turn-off Propagation Delay vs. Temperature



**Figure 8.** Rise Time vs. Supply Voltage



**Figure 9.** Rise Time vs. Temperature

## Typical Performance Characteristics (Cont.)

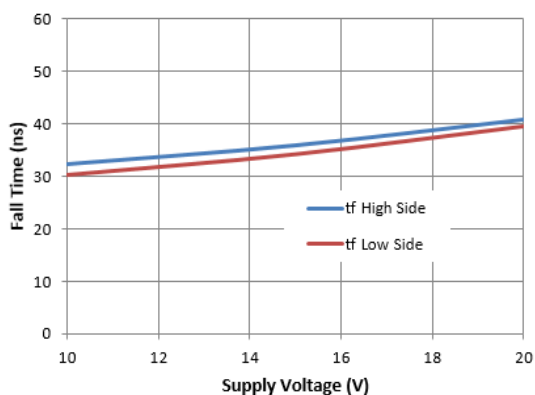


Figure 10. Fall Time vs. Supply Voltage

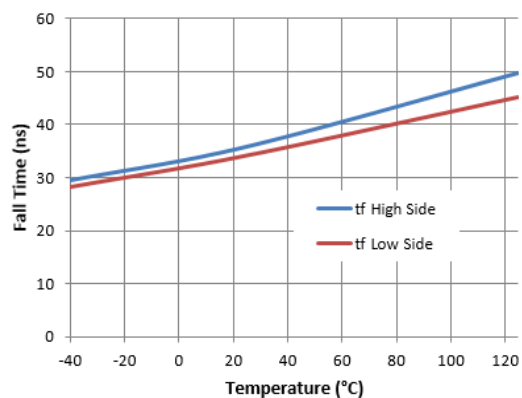


Figure 11. Fall Time vs. Temperature

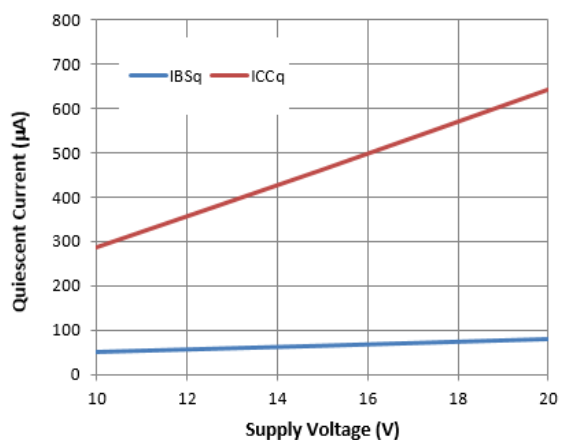


Figure 12. Quiescent Current vs. Supply Voltage

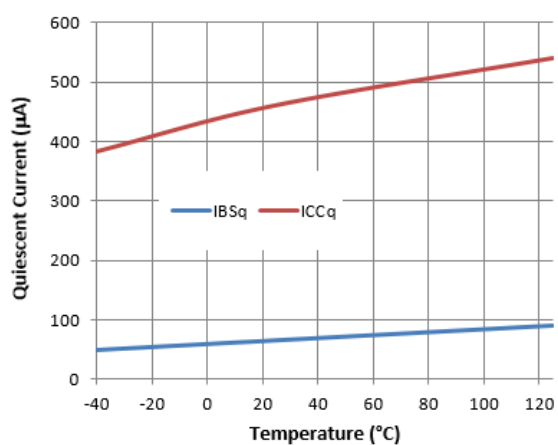


Figure 13. Quiescent Current vs. Temperature

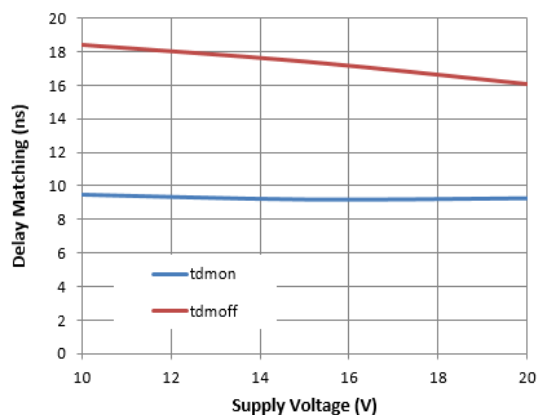


Figure 14. Delay Matching vs. Supply Voltage

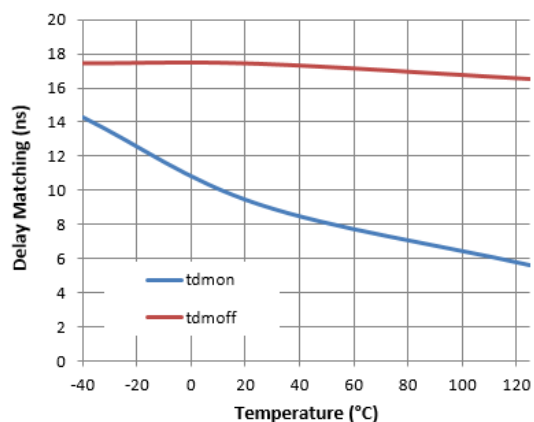


Figure 15. Delay Matching vs. Temperature

## Typical Performance Characteristics (Cont.)

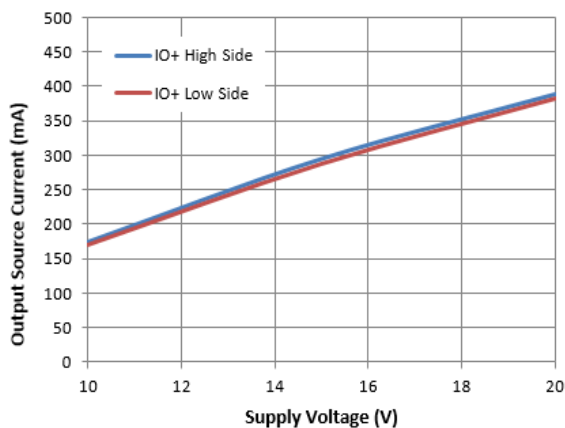


Figure 16. Output Source Current vs. Supply Voltage

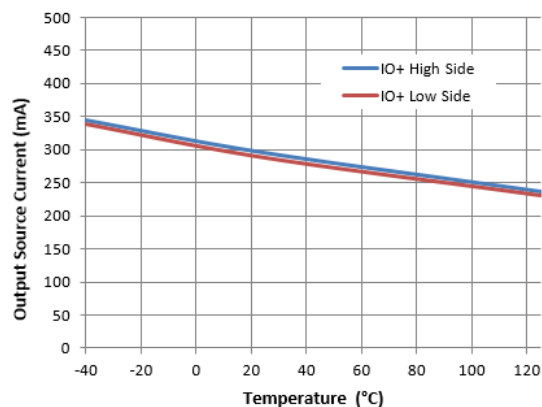


Figure 17. Output Source Current vs. Temperature

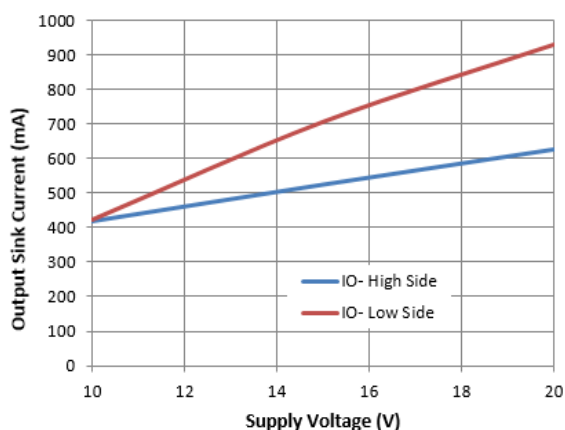


Figure 18. Output Sink Current vs. Supply Voltage

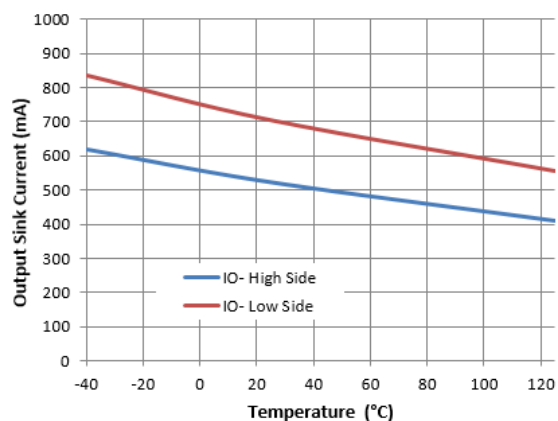


Figure 19. Output Sink Current vs. Temperature

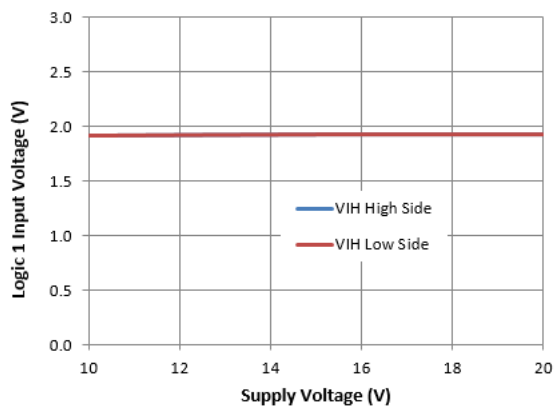


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

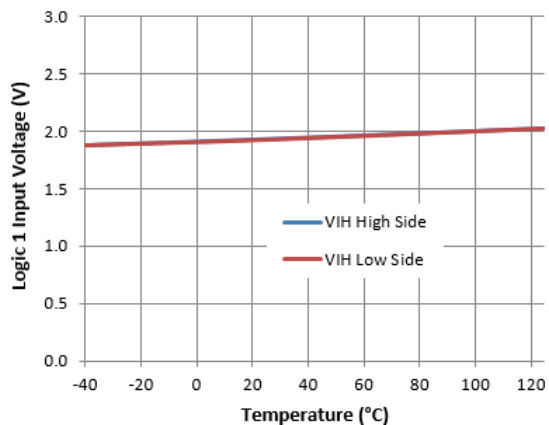


Figure 21. Logic 1 Input Voltage vs. Temperature

## Typical Performance Characteristics (Cont.)

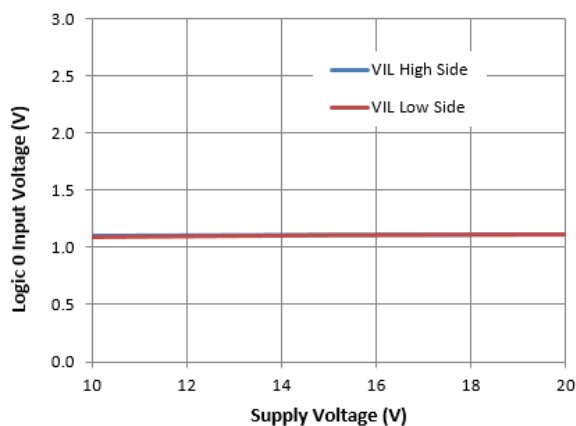


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

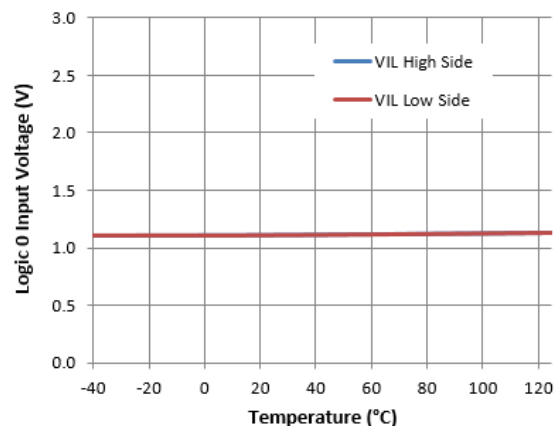


Figure 23. Logic 0 Input Voltage vs. Temperature

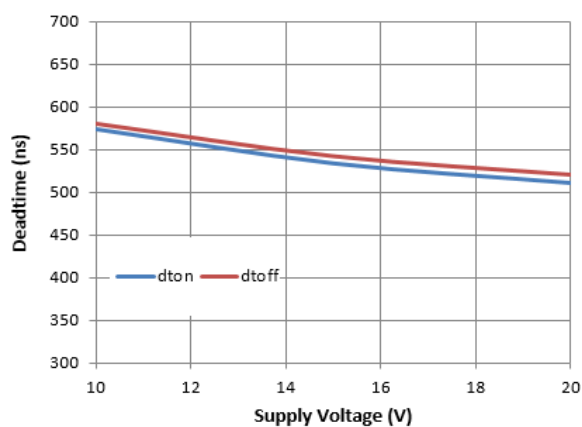


Figure 24. Deadtime vs. Supply Voltage

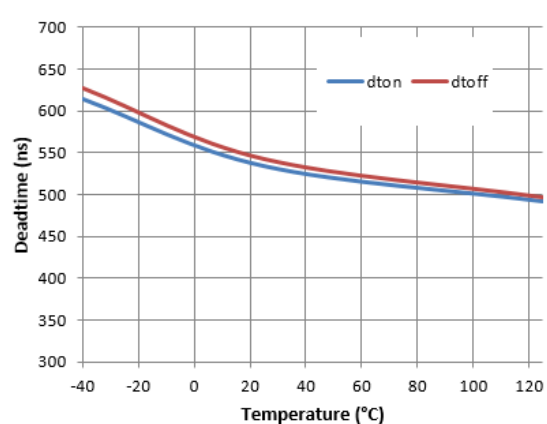


Figure 25. Deadtime vs. Temperature

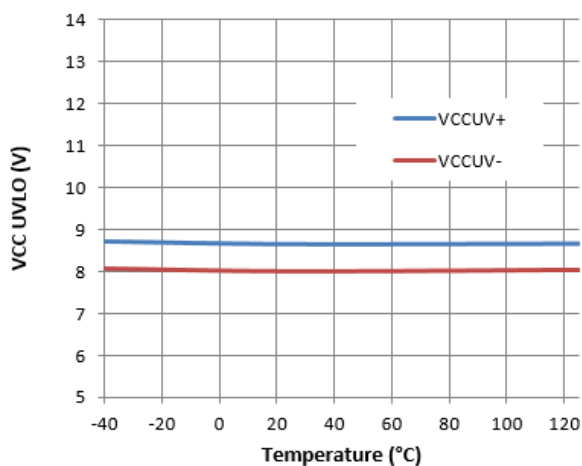


Figure 26. VCC UVLO vs. Temperature

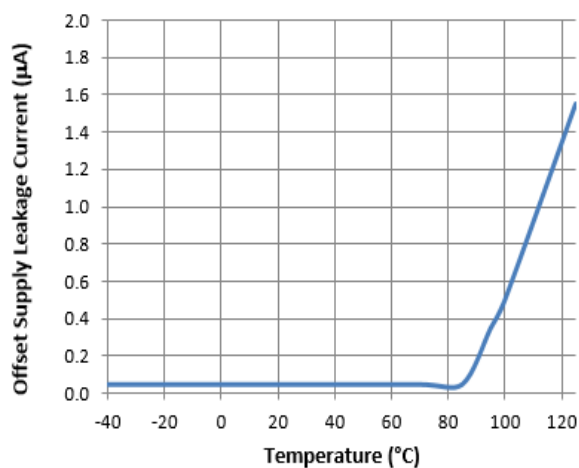
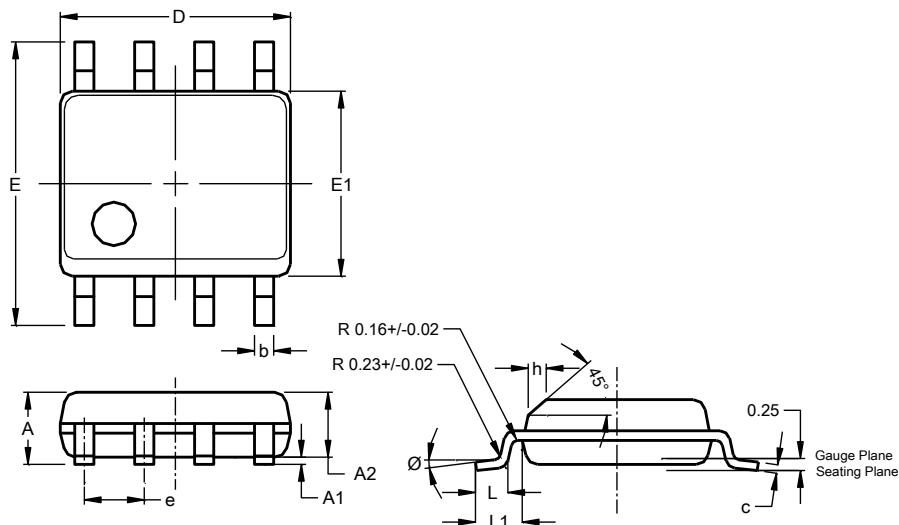


Figure 27. Offset Supply Leakage Current vs. Temperature

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SO-8 (Type TH)

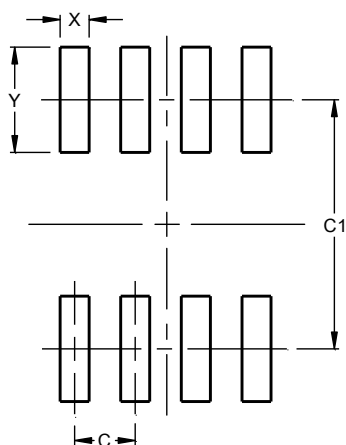


SO-8 (Type TH)			
Dim	Min	Max	Typ
A	1.35	1.75	--
A1	0.10	0.25	--
A2	--	--	1.45
b	0.35	0.51	--
c	0.190	0.248	--
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	--	--	1.27
h	0.25	0.50	--
L	0.41	1.27	--
L1	--	--	1.04
Ø	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note : For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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